ABSTRACT OF THE DISCLOSURE

TITLE OF INVENTION: **APPARATUS AND METHOD FOR PRODUCING AN ELECTRONIC COMPONENT PROVIDED WITH BUMPS**

The invention provides an apparatus and a method for producing an electronic component provided with bumps, in which the operation of placing a solder ball serving as a material of a bump onto an electrode of a work is monitored, and if a solder ball placing failure is detected, a recovering operation is automatically performed. In the apparatus and method of the invention, a head is moved to a location above a solder ball supplying unit so as to pick up solder balls by means of suction. The head is then moved to a location above a flux reservoir so that the solder balls are coated with flux. The head is further moved to a location above a substrate and the solder balls are placed on electrodes of the substrate. The substrate is then observed using a camera to decide whether solder balls are correctly placed on the electrodes. If yes, the substrate is transferred into a heating furnace. On the other hand, if a solder ball placing failure is detected, the solder balls are removed using a nozzle and the step of placing solder balls is performed again.

Figure 2